

IN THE CLAIMS:

Pursuant to 37 C.F.R. § 1.121(c)(3), all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity.

Please cancel claim 6 without prejudice or disclaimer.

1. A method for applying a material between a semiconductor device having a surface and a substrate having a surface, said method comprising:
applying a wetting agent layer to one of said surface of said semiconductor device and said surface of said substrate; and
applying a flowable material between the substrate and the semiconductor device.

2. (Previously Amended) The method according to claim 1, wherein said semiconductor device is attached to said substrate.

3. (Amended) The method of claim 1, wherein said wetting agent layer includes a layer of silane-based material. *D*

4. (Previously Amended) The method according to claim 1, wherein said applying said wetting agent layer comprises any one of a dispensing method, a brushing method, and a spraying method.

5. The method according to claim 1, wherein said wetting agent layer comprises at least one layer.

7. The method according to claim 1, wherein said wetting agent layer comprises a plurality of layers.

8. (Amended) The method according to claim 1, wherein said wetting agent layer comprises one of glycidoxypropyltrimethoxysilane and ethyltrimethoxysilane.

9. (Twice Amended) The method according to claim 1, wherein said applying said wetting agent layer comprises providing a material for increasing the surface tension to one of said surface of said semiconductor device and said surface of said substrate for the application of an underfill material.

10. (Previously Amended) A method for applying a material between a semiconductor device and a substrate, said method comprising:
providing a semiconductor device having an active surface, another surface, a first end, a second end, a first lateral side, and a second lateral side, said first end, said second end, said first lateral side, and said second lateral side forming at least a portion of a periphery of said semiconductor device;
providing a substrate having an upper surface, a first side wall, a second side wall, a first lateral side wall and a second lateral side wall;
applying a wetting agent layer to one of said active surface of said semiconductor device and said upper surface of said substrate; and
applying a flowable material between said semiconductor device and said substrate.

11. (Previously Amended) The method according to claim 10, wherein said flowable material is applied substantially adjacent to at least one end of said semiconductor device.

12. (Previously Amended) The method according to claim 10, wherein said flowable material substantially fills a gap between said semiconductor device and said substrate.

13. The method according to claim 10, wherein said substrate includes an aperture extending through said substrate.

14. (Previously Amended) The method according to claim 13, wherein said aperture is located adjacent to said another surface of said semiconductor device.

15. (Previously Amended) The method according to claim 10, wherein said flowable material is provided substantially adjacent to said at least a portion of the periphery of said semiconductor device to fill a gap between said substrate and said semiconductor device.

16. The method according to claim 10, further comprising:
elevating at least said first side wall of said substrate and said first end of said semiconductor device.

17. (Previously Amended) The method according to claim 16, wherein said elevating said first side wall of said substrate comprises placing said substrate on a support structure and elevating at least one portion of said support structure.

18. The method according to claim 16, further comprising:
providing a dam on the substrate adjacent to at least one of said first end, said second end, said first lateral side and said second lateral side of said semiconductor device.

19. The method according to claim 18, wherein said dam extends to substantially between said semiconductor device and said substrate.

20. The method of claim 10, further comprising:
vibrating one of said semiconductor device and said substrate.

21. The method according to claim 20, wherein said vibrating one of said semiconductor device and said substrate comprises placing said substrate on a support structure and vibrating said support structure.

22. (Previously Amended) The method according to claim 10, wherein said applying said flowable material comprises:
providing said flowable material substantially adjacent said first end of said semiconductor device for filling between said substrate and said semiconductor device by one or more forces acting upon said flowable material.

23. (Previously Amended) The method according to claim 10, wherein said substrate includes at least one aperture extending through said substrate and substantially located adjacent to said another surface of said semiconductor device.

24. (Previously Amended) The method according to claim 23, wherein said flowable material is provided through said at least one aperture of said substrate substantially filling a gap between said substrate and said semiconductor device.

25. (Previously Amended) The method according to claim 18, wherein said applying said flowable material comprises:
providing said flowable material substantially adjacent to said first end of said semiconductor device for filling a gap between said substrate and said semiconductor device.

26. (Previously Amended) The method according to claim 18, wherein said applying said flowable material comprises:
providing said flowable material substantially adjacent to said first end and one of said first

lateral side and said second lateral side of said semiconductor device for filling a gap between said substrate and said semiconductor device.

27. (Previously Amended) The method according to claim 18, wherein said substrate includes at least one aperture extending therethrough and substantially located adjacent to said another surface of said semiconductor device.

28. The method according to claim 27, wherein said flowable material is provided through said at least one aperture.

29. The method according to claim 28, wherein said flowable material is provided from below said substrate.

30. (Previously Amended) The method according to claim 28, wherein said flowable material is provided through said at least one aperture contacting at least a portion of said another surface of said semiconductor device.

31. (Previously Amended) The method according to claim 10, wherein said applying said flowable material between said semiconductor device and said substrate further comprises placing said semiconductor device and said substrate in a chamber, said chamber having an atmosphere therein having a variable pressure.

32. (Previously Amended) The method according to claim 31, further comprising: varying the pressure of said atmosphere in said chamber for said flowable material substantially filling a gap between said semiconductor device and said substrate.

58. (Previously Twice Amended) A method for attaching a semiconductor assembly, said method comprising:

providing a semiconductor device having an active surface;

providing a substrate having an upper surface;

applying a wetting agent layer to one of said active surface of said semiconductor device and said upper surface of said substrate;

connecting said semiconductor device to said substrate so that said active surface of said semiconductor device faces said upper surface of said substrate; and

applying an underfill material between the substrate and the semiconductor device.

59. (Previously Amended) The method according to claim 58, wherein applying said wetting agent layer comprises any one of a dispensing method, a brushing method, and a spraying method.

60. (Previously Amended) The method according to claim 58, wherein said wetting agent layer comprises at least one layer.

61. (Three Times Amended) The method according to claim 58, wherein said wetting agent layer comprises a silane-based material. D

62. (Twice Amended) A method for attaching a semiconductor assembly, said method comprising:

providing a semiconductor device having an active surface, a first end, a second end, a first lateral side end and a second lateral side end;

providing a substrate having an upper surface, a first side wall, a second side wall, a first lateral side wall and a second lateral side wall;

applying a silane-based material layer to one of a portion of said active surface of said

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semiconductor device and a portion of said upper surface of said substrate; connecting said semiconductor device to said substrate so that said active surface of said semiconductor device faces said upper surface of said substrate; and applying an underfill material between said semiconductor device and said substrate.

Please add the following new claim:

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--63. The method according to claim 61, wherein said wetting agent layer comprises one of glycidoxypropyltrimethoxysilane and ethyltrimethoxysilane.--